



**CY74FCT2543T**  
**8-BIT LATCHED TRANSCEIVER**  
**WITH 3-STATE OUTPUTS**

SCCS042C – SEPTEMBER 1994 – REVISED NOVEMBER 2001

**PIN DESCRIPTION**

NAME	DESCRIPTION
$\overline{OEAB}$	A-to-B output-enable input (active low)
$\overline{OEBA}$	B-to-A output-enable input (active low)
$\overline{CEAB}$	A-to-B enable input (active low)
$\overline{CEBA}$	B-to-A enable input (active low)
$\overline{LEAB}$	A-to-B latch-enable input (active low)
$\overline{LEBA}$	B-to-A latch-enable input (active low)
A	A-to-B data inputs or B-to-A 3-state outputs
B	B-to-A data inputs or A-to-B 3-state outputs

**ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QSOP – Q	Tape and reel	5.3	CY74FCT2543CTQCT	FCT2543C
	SOIC – SO	Tube	5.3	CY74FCT2543CTSOC	FCT2543C
		Tape and reel	5.3	CY74FCT2543CTSOCT	
	QSOP – Q	Tape and reel	6.5	CY74FCT2543ATQCT	FCT2543A
	SOIC – SO	Tube	6.5	CY74FCT2543ATSOC	FCT2543A
		Tape and reel	6.5	CY74FCT2543ATSOCT	
QSOP – Q	Tape and reel	8.5	CY74FCT2543TQCT	FCT2543	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

**FUNCTION TABLE**

INPUTS			LATCH A-TO-B‡	OUTPUT B
CEAB	LEAB	OEAB		
H	X	X	Storing	Z
X	H	X	Storing	X
X	X	H	X	Z
L	L	L	Transparent	Current A inputs
L	H	L	Storing	Previous A inputs

‡ Before  $\overline{LEAB}$  low-to-high transition

H = High logic level, L = Low logic level, X = Don't care,

Z = High-impedance state

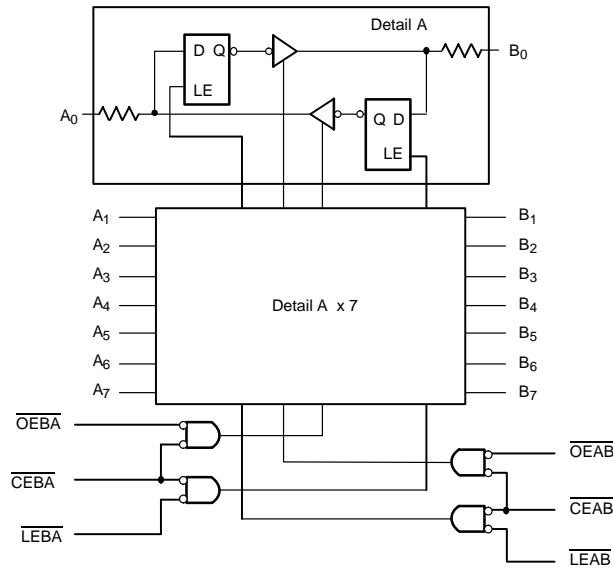
A-to-B data flow shown; B-to-A is the same, except using  $\overline{CEBA}$ ,  $\overline{LEBA}$ , and  $\overline{OEBA}$ .



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## functional block diagram



## absolute maximum rating over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential .....	-0.5 V to 7 V
DC input voltage range .....	-0.5 V to 7 V
DC output voltage range .....	-0.5 V to 7 V
DC output current (maximum sink current/pin) .....	120 mA
Package thermal impedance, $\theta_{JA}$ (see Note 1): Q package .....	61°C/W
SO package .....	46°C/W
Ambient temperature range with power applied, $T_A$ .....	-65°C to 135°C
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	4.75	5	5.25	V
$V_{IH}$	High-level input voltage	2			V
$V_{IL}$	Low-level input voltage			0.8	V
$I_{OH}$	High-level output current			-15	mA
$I_{OL}$	Low-level output current			12	mA
$T_A$	Operating free-air temperature	-40		85	°C

NOTE 2: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation.

# CY74FCT2543T

## 8-BIT LATCHED TRANSCEIVER

### WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
$V_{IK}$	$V_{CC} = 4.75\text{ V}$ ,	$I_{IN} = -18\text{ mA}$	-0.7	-1.2		V	
$V_{OH}$	$V_{CC} = 4.75\text{ V}$ ,	$I_{OH} = -15\text{ mA}$	2.4	3.3		V	
$V_{OL}$	$V_{CC} = 4.75\text{ V}$ ,	$I_{OL} = 12\text{ mA}$		0.3	0.55	V	
$R_{out}$	$V_{CC} = 4.75\text{ V}$ ,	$I_{OL} = 12\text{ mA}$	20	25	40	$\Omega$	
$V_{hys}$	All inputs			0.2		V	
$I_{IH}$	$V_{CC} = 5.25\text{ V}$	$V_{IN} = V_{CC}$			5	$\mu\text{A}$	
		$V_{IN} = 2.7\text{ V}$			$\pm 1$		
$I_{IL}$	$V_{CC} = 5.25\text{ V}$ ,	$V_{IN} = 0.5\text{ V}$			$\pm 1$	$\mu\text{A}$	
$I_{OZH}$	$V_{CC} = 5.25\text{ V}$ ,	$V_{OUT} = 2.7\text{ V}$			15	$\mu\text{A}$	
$I_{OZL}$	$V_{CC} = 5.25\text{ V}$ ,	$V_{OUT} = 0.5\text{ V}$			-15	$\mu\text{A}$	
$I_{OS}^{\ddagger}$	$V_{CC} = 5.25\text{ V}$ ,	$V_{OUT} = 0\text{ V}$	-60	-120	-225	mA	
$I_{off}$	$V_{CC} = 0\text{ V}$ ,	$V_{OUT} = 4.5\text{ V}$			$\pm 1$	$\mu\text{A}$	
$I_{CC}$	$V_{CC} = 5.25\text{ V}$ ,	$V_{IN} \leq 0.2\text{ V}$ , $V_{IN} \geq V_{CC} - 0.2\text{ V}$		0.1	0.2	mA	
$\Delta I_{CC}$	$V_{CC} = 5.25\text{ V}$ , $V_{IN} = 3.4\text{ V}^{\S}$ , $f_1 = 0$ , Outputs open			0.5	2	mA	
$I_{CCD}^{\uparrow}$	$V_{CC} = 5.25\text{ V}$ , One input switching at 50% duty cycle, Outputs open, $\overline{CEAB}$ and $\overline{OEAB} = \text{LOW}$ , $\overline{CEBA} = \text{HIGH}$ , $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$			0.06	1.2	mA/MHz	
$I_C^{\#}$	$V_{CC} = 5.25\text{ V}$ , $f_0 = 10\text{ MHz}$ , Outputs open, $\overline{CEAB}$ and $\overline{OEAB} = \text{LOW}$ , $\overline{CEBA} = \text{HIGH}$ , $f_0 = \overline{LEAB} = 10\text{ MHz}$	One bit switching at $f_1 = 5\text{ MHz}$ at 50% duty cycle	$V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$		0.7	1.4	mA
			$V_{IN} = 3.4\text{ V}$ or GND		1.2	3.4	
		Eight bits switching at $f_1 = 5\text{ MHz}$ at 50% duty cycle	$V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$		2.8	5.6	
			$V_{IN} = 3.4\text{ V}$ or GND		5.1	14.6	
$C_i$				5	10	pF	
$C_o$				9	12	pF	

† Typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests,  $I_{OS}$  tests should be performed last.

§ Per TTL-driven input ( $V_{IN} = 3.4\text{ V}$ ); all other inputs at  $V_{CC}$  or GND

↑ This parameter is derived for use in total power-supply calculations.

#  $I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

$I_C$  = Total supply current

$I_{CC}$  = Power-supply current with CMOS input levels

$\Delta I_{CC}$  = Power-supply current for a TTL high input ( $V_{IN} = 3.4\text{ V}$ )

$D_H$  = Duty cycle for TTL inputs high

$N_T$  = Number of TTL inputs at  $D_H$

$I_{CCD}$  = Dynamic current caused by an input transition pair (HLH or LHL)

$f_0$  = Clock frequency for registered devices, otherwise zero

$f_1$  = Input signal frequency

$N_1$  = Number of inputs changing at  $f_1$

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the  $I_C$  formula.



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**timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)**

PARAMETER		CY74FCT2543T		CY74FCT2543AT		CY74FCT2543CT		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$t_w$	Pulse duration, $\overline{LEBA}$ or $\overline{LEAB}$ low	5		5		5		ns
$t_{su}$	Setup time, high or low	A or B before $\overline{LEBA}\downarrow$ or $\overline{LEAB}\downarrow$		2		2		ns
$t_h$	Hold time, high or low	A or B after $\overline{LEBA}\downarrow$ or $\overline{LEAB}\downarrow$		2		2		ns

**switching characteristics over operating free-air temperature range (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT2543T		CY74FCT2543AT		CY74FCT2543CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A or B	B or A	2.5	8.5	2.5	6.5	2.5	5.5	ns
$t_{PHL}$									
$t_{PLH}$	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	2.5	12.5	2.5	8	2.5	7	ns
$t_{PHL}$									
$t_{PZH}$	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	2	12	2	9	2	8	ns
$t_{PZL}$									
$t_{PZH}$	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	2	12	2	9	2	8	ns
$t_{PZL}$									
$t_{PHZ}$	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	2	9	2	7.5	2	6.5	ns
$t_{PLZ}$									
$t_{PHZ}$	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	2	9	2	7.5	2	6.5	ns
$t_{PLZ}$									

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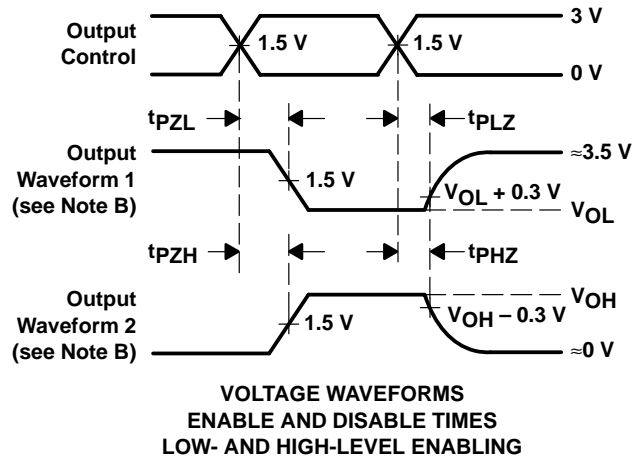
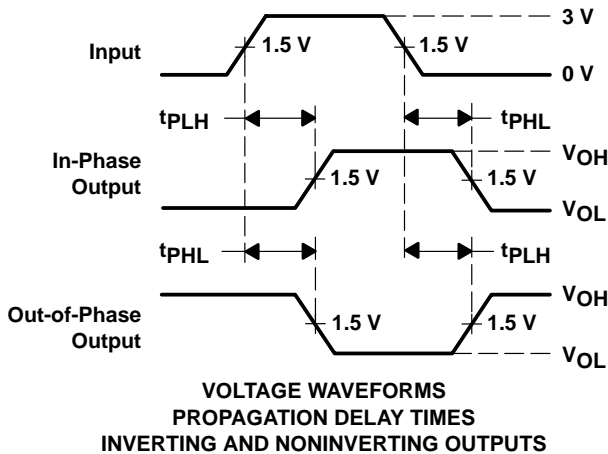
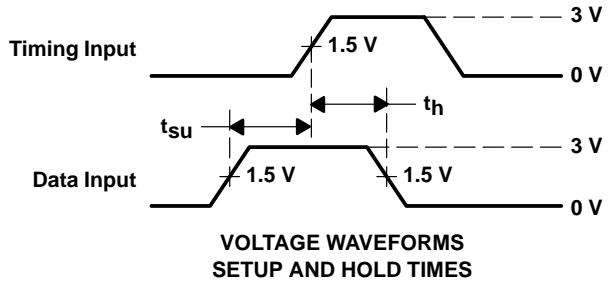
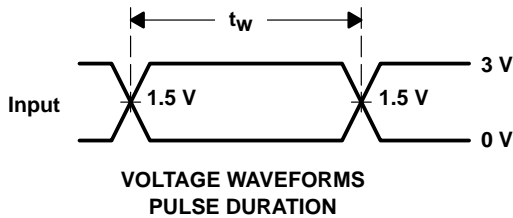
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**PARAMETER MEASUREMENT INFORMATION**



**LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS**

**LOAD CIRCUIT FOR 3-STATE OUTPUTS**



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">CY74FCT2543ATQCT</a>	Active	Production	SSOP (DBQ)   24	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2543A
CY74FCT2543ATQCT.B	Active	Production	SSOP (DBQ)   24	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2543A
<a href="#">CY74FCT2543ATSOC</a>	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2543A
CY74FCT2543ATSOC.B	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2543A
<a href="#">CY74FCT2543CTQCT</a>	Active	Production	SSOP (DBQ)   24	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2543C
CY74FCT2543CTQCT.B	Active	Production	SSOP (DBQ)   24	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2543C
CY74FCT2543CTQCTG4	Active	Production	SSOP (DBQ)   24	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2543C
CY74FCT2543CTQCTG4.B	Active	Production	SSOP (DBQ)   24	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT2543C
<a href="#">CY74FCT2543CTSOC</a>	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2543C
CY74FCT2543CTSOC.B	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT2543C

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT2543ATQCT	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT2543CTQCT	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT2543CTQCTG4	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT2543ATQCT	SSOP	DBQ	24	2500	353.0	353.0	32.0
CY74FCT2543CTQCT	SSOP	DBQ	24	2500	353.0	353.0	32.0
CY74FCT2543CTQCTG4	SSOP	DBQ	24	2500	353.0	353.0	32.0

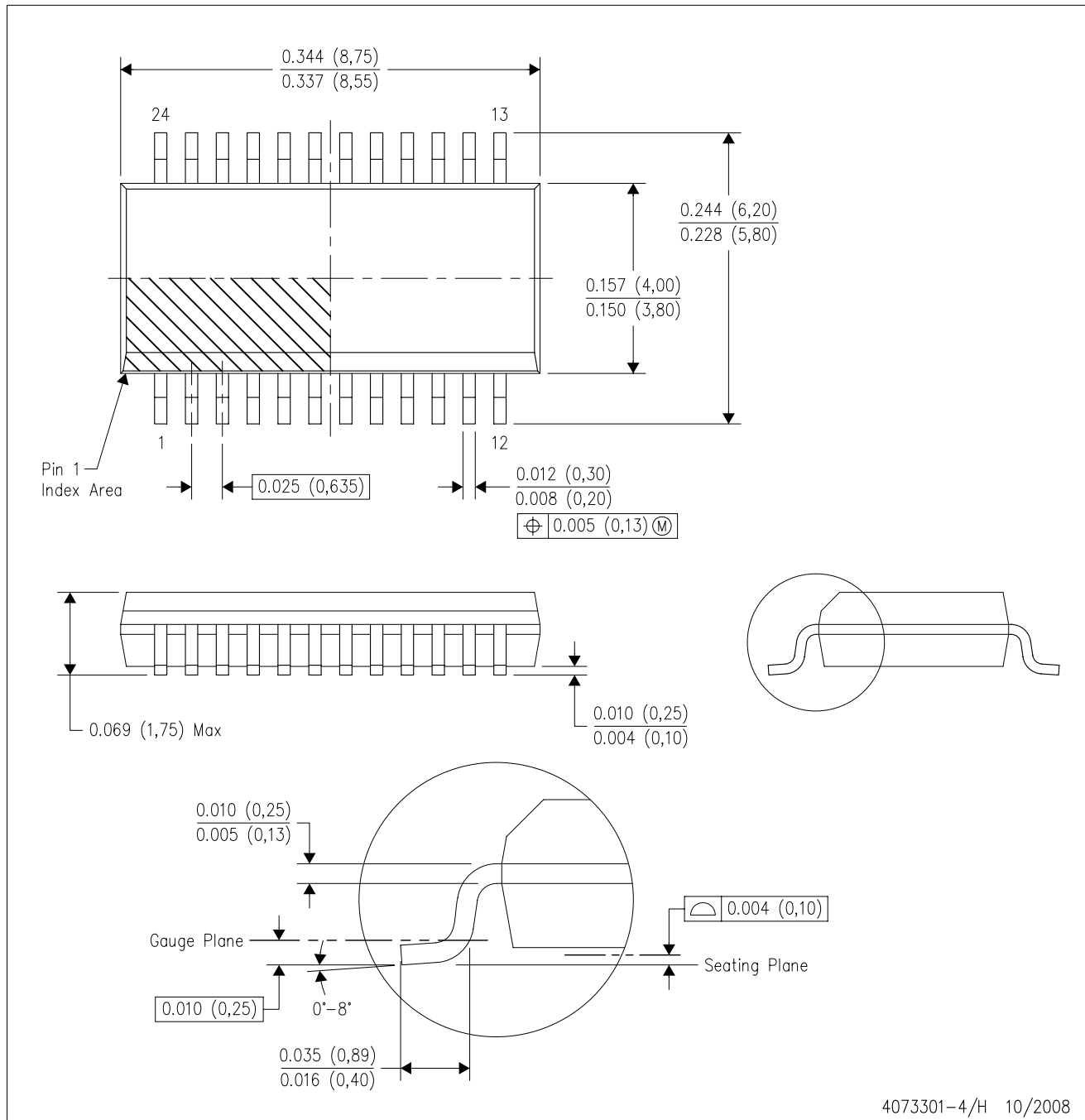
**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CY74FCT2543ATSOC	DW	SOIC	24	25	506.98	12.7	4826	6.6
CY74FCT2543ATSOC.B	DW	SOIC	24	25	506.98	12.7	4826	6.6
CY74FCT2543CTSOC	DW	SOIC	24	25	506.98	12.7	4826	6.6
CY74FCT2543CTSOC.B	DW	SOIC	24	25	506.98	12.7	4826	6.6

DBQ (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - D. Falls within JEDEC MO-137 variation AE.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.

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